

Abstract

Method of Forming an Integrated Circuit and Related Integrated Circuit

5 A method (100) of forming an integrated circuit is disclosed. The method comprises: (i) forming at least a pair of optoelectronic devices from at least a first wafer material arranged on a semiconductor substrate, the first wafer material different to silicon; (ii) etching the first wafer material to form a first recess to be filled with a second material; (iii) processing (104) the second
10 material to form a waveguide for coupling the pair of optoelectronic devices to define an optical interconnect; and (iv) bonding (106) at least one partially processed CMOS device layer having at least one transistor to the second semiconductor substrate to form the integrated circuit, the partially processed CMOS device layer arranged adjacent to the optical interconnect. An integrated
15 circuit is also disclosed.

FIG. 1